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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/615,038	07/08/2003	Young-Soo Kim	29926/39505	3909
4743 7.	590 09/29/2004		EXAMINER	
MARSHALL, GERSTEIN & BORUN LLP			SMITH, BRADLEY	
6300 SEARS T 233 S. WACKI			ART UNIT	PAPER NUMBER
CHICAGO, IL	60606		2824	
			DATE MAILED: 09/29/200	4

Please find below and/or attached an Office communication concerning this application or proceeding.

			//YX
	Application No.	Applicant(s)	74
	10/615,038	KIM, YOUNG-SOO	
Office Action Summary	Examiner	Art Unit	
	Bradley K Smith	2824	
The MAILING DATE of this communica Period for Reply	ntion appears on the cover sheet with	the correspondence addre	SS
A SHORTENED STATUTORY PERIOD FOR THE MAILING DATE OF THIS COMMUNICA - Extensions of time may be available under the provisions of after SIX (6) MONTHS from the mailing date of this communi - If the period for reply specified above is less than thirty (30) of If NO period for reply is specified above, the maximum statut. - Failure to reply within the set or extended period for reply will Any reply received by the Office later than three months after earned patent term adjustment. See 37 CFR 1.704(b).	ATION. 37 CFR 1.136(a). In no event, however, may a repication. lays, a reply within the statutory minimum of thirty (ory period will apply and will expire SIX (6) MONTH, by statute, cause the application to become ABAI	ly be timely filed 30) days will be considered timely. IS from the mailing date of this comm NDONED (35 U.S.C. § 133).	unication.
Status			
1) Responsive to communication(s) filed	on .		
	 ⊠ This action is non-final.		
3) Since this application is in condition for closed in accordance with the practice	, , , , , , , , , , , , , , , , , , ,	•	erits is
Disposition of Claims			
4) ☐ Claim(s) 1-7 is/are pending in the applied 4a) Of the above claim(s) is/are 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1 and 3 is/are rejected. 7) ☐ Claim(s) 2,4-7 is/are objected to. 8) ☐ Claim(s) are subject to restriction	withdrawn from consideration.		
Application Papers			
9) ☐ The specification is objected to by the E	Examiner.		
10)⊠ The drawing(s) filed on <u>08 July 2003</u> is	/are: a)⊠ accepted or b)□ objecte	ed to by the Examiner.	
Applicant may not request that any objection	on to the drawing(s) be held in abeyand	e. See 37 CFR 1.85(a).	
Replacement drawing sheet(s) including th 11) The oath or declaration is objected to b	•	•	• •
Priority under 35 U.S.C. § 119		•	
12) △ Acknowledgment is made of a claim for a) △ All b) ☐ Some * c) ☐ None of: 1. △ Certified copies of the priority do	ocuments have been received. Ocuments have been received in Apolithe priority documents have been real Bureau (PCT Rule 17.2(a)).	olication No eceived in this National Sta	ıge
Attachment(s)	. □		
1) ⊠ Notice of References Cited (PTO-892) 2) ☑ Notice of Draftsperson's Patent Drawing Review (PTO	0-948) Paper No(s)/	mmary (PTO-413) Mail Date	
Information Disclosure Statement(s) (PTO-1449 or PT Paper No(s)/Mail Date <u>7/8/03</u> .		ormal Patent Application (PTO-15 <u>n notes</u> .	2)

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DETAILED ACTION

Claim Objections

1. Claim 4 and 6 are objected to because of the following informalities: TiCl4 should be TiCl₄. Appropriate correction is required.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

3. Claim 1 is rejected under 35 U.S.C. 102(e) as being anticipated by Park et al. (US Pregrant Publication 2003/0003649). Park et al. disclose forming a lower electrode on a semiconductor substrate; forming a dielectric layer on the lower electrode; loading the semiconductor substrate containing the dielectric layer into a deposition chamber (the examiner understands that this step would be inherent, and well known to one of ordinary skill in the art); nitriding a surface of the dielectric layer while NH₃ gas is flowed into the deposition chamber (paragraph 0021); and forming an upper layer by using a source gas NH₃, containing Titanium (Ti) on the nitrated surface of the dielectric layer through an atomic layer deposition (ALD) method (paragraph 0028).

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4. Claims 1 and 3 are rejected under 35 U.S.C. 102(e) as being anticipated by Sneh et al. (US Patent 6,551,399). With regards to claim 1, Sneh et al. disclose forming a lower electrode on a semiconductor substrate; forming a dielectric layer on the lower electrode; loading the semiconductor substrate containing the dielectric layer into a deposition chamber (the examiner understands that this step would be inherent, and well known to one of ordinary skill in the art); nitriding a surface of the dielectric layer while NH₃ gas is flowed into the deposition chamber; and forming an upper layer by using a source gas NH₃, containing Titanium (Ti) on the nitrated surface of the dielectric layer through an atomic layer deposition (ALD) method (see example 19). With regards to claim 3, Sneh et al. disclose loading a semiconductor substrate containing a formed on a lower electrode into a dielectric layer deposition chamber (the examiner understands that this step would be inherent, and well known to one of ordinary skill in the art); and forming an upper electrode containing Titanium (Ti) on the dielectric layer through an atomic layer deposition (ALD) method using a source gas NH₃ (example 19).

Allowable Subject Matter

- 5. Claims 2 and 4-7 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
- 6. The following is a statement of reasons for the indication of allowable subject matter: the prior art of record neither teaches nor suggests flowing the NH₃ source gas in at 300 sccm to 1000 sccm for 10 to 120 seconds (claim 2), wherein the flow rate is

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controlled by opening a valve (claims 4 and 5), TiCl₄ feeding time is mandated to be timed, wherein initial 50 cycles lapse f or about 0.05 seconds to about 0.2 seconds and the rest lapses for about 0.5 seconds to about 0.2 seconds (claim 6), absorbing the TiCl₄ onto the dielectric layer by feeding the TiCl₄; feeding the TiCl₄ gas in order to make it absorbed on the dielectric layer; purging a remnant of the TiCl₄ gas remaining after the absorption; feeding NH₃ gas on a surface of the dielectric layer on which the TiCl₄ is already absorbed; and purging a remnant of the NH₃ gas and a by-product which is formed by a chemical reaction between the NH₃ and the TiCl₄ (claim 7).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Bradley K Smith whose telephone number is (571) 272-1884. The examiner can normally be reached on 10-6 Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Richard Elms can be reached on (571) 272-1869. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Brad Smith

Patent Examiner